SDAS232A - DECEMBER 1983 - REVISED JANUARY 1995

 3-State Buffer-Type Outputs Drive Bus Lines Directly 	DW OR NT PACKAG (TOP VIEW)					
Bus-Structured Pinout	OE I	U ₂₄] _{VCC}				
 Provides Extra Bus-Driving Latches 	1D 2	23 1 1Q				
Necessary for Wider Address/Data Paths or	2D 🛚 3	22] 2Q				
Buses With Parity	3D 🛮 4	21 🛮 3Q				
Buffered Control Inputs to Reduce	4D 🛮 5	20] 4Q				
dc Loading Effects	5D [6	19 🛮 5Q				
Power-Up High-Impedance State	6D 🛮 7	18 🛮 6Q				
Package Options Include Plastic	7D []8	17 🛮 7Q				
Small-Outline (DW) Packages and Standard	8D []9	16 🛮 8Q				
Plastic (NT) 300-mil DIPs	9D [10	15 3Q				
(11)	CLR [11	14 PRE				
description	GND [12	2 13 LE				

This 9-bit bus-interface D-type latch features 3-state outputs designed specifically for driving

highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The nine latches are transparent D-type latches with noninverting data (D) inputs.

A buffered output-enable (\overline{OE}) input places the nine outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

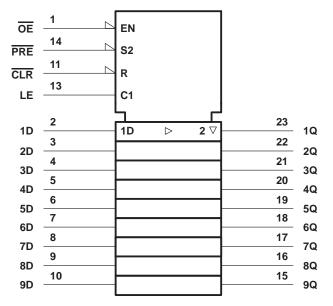
OE does not affect the internal operation of the latches. Previously stored data can be retained or new data can be entered while the outputs are off.

The SN74ALS843 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

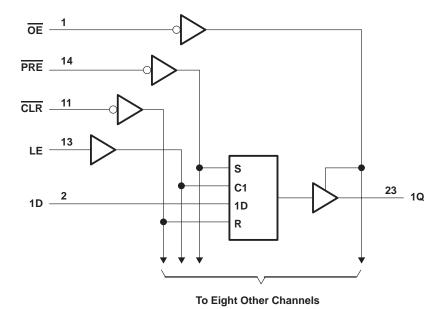
		INPUTS			OUTPUT
PRE	CLR	OE	LE	D	Q
L	Х	L	Х	Х	Н
Н	L	L	X	X	L
Н	Н	L	Н	L	L
Н	Н	L	Н	Н	Н
Н	Н	L	L	X	Q ₀
X	X	Н	X	X	Z

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V _I	
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range	

recommended operating conditions

			MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	V
VIH	High-level input voltage		2			V
V _{IL}	Low-level input voltage				0.8	V
ІОН	High-level output current				-2.6	mA
loL	Low-level output current				24	mA
	Pulse duration	CLR or PRE low	35			
t _W	Pulse duration	LE high	20			ns
t _{su}	Setup time, data before LE↓		10			ns
t _h	Hold time, data after LE \downarrow		5			ns
T _A	Operating free-air temperature		0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST COND	DITIONS	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = 4.5 V,	I _I = -18 mA			-1.2	V
Vari	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V
Voн	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -2.6 \text{ mA}$	2.4	3.2		v
Voi	V45V	I _{OL} = 12 mA		0.25	0.4	V
VoL	$V_{CC} = 4.5 \text{ V}$	I _{OL} = 24 mA		0.35	0.5	V V
I _{OZH}	$V_{CC} = 5.5 V,$	V _O = 2.7 V			20	μΑ
lozL	$V_{CC} = 5.5 \text{ V},$	V _O = 0.4 V			-20	μΑ
IĮ	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1	mA
IIH	V _{CC} = 5.5 V,	V _I = 2.7 V			20	μΑ
l _{IL}	$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			-0.1	mA
I _O §	V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	mA
		Outputs high		21	36	
Icc	$V_{CC} = 5.5 V$	Outputs low		41	67	mA
		Outputs disabled		25	42	

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

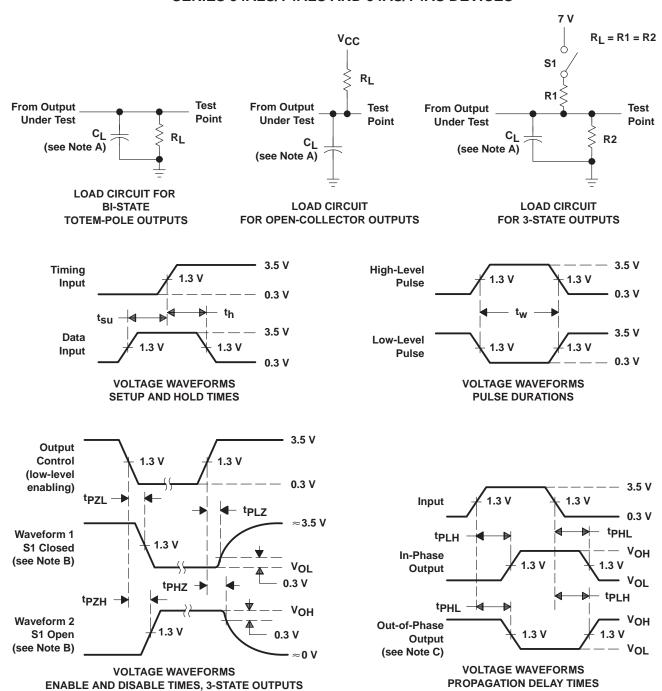
SN74ALS843 9-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS SDAS232A - DECEMBER 1983 - REVISED JANUARY 1995

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 ^{\circ}$ $C_{L} = 50 \text{ pF}$ $R1 = 500 \Omega$ $R2 = 500 \Omega$ $T_{A} = \text{MIN to}$	UNIT		
			MIN	MAX		
^t PLH	D		2	13	ns	
^t PHL	ט	Q	4	18	115	
^t PLH	LE		5	21	ns	
^t PHL	LL	Q	8	26		
^t PLH	PRE		5	22	ns	
^t PHL	CLR	Q	6	23	115	
^t PZH			2	12		
tPZL	ŌĒ	Q	4	14	ns	
^t PHZ	ŌĒ	0	2	10	ne	
tPLZ	OE .	Q	2	12	ns	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_{Γ} = t_{f} = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74ALS843DWR	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS843	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS843DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74ALS843DWR	SOIC	DW	24	2000	350.0	350.0	43.0	

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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